F-B-M8503ESB

Electrical and Acoustical Parameter

Rated Voltage (Vp-p) * 3.0

Operating Voltage (Vp-p) 1.0 – 4.5

Coil Resistance (Ω) 20±10

Rated Current (mA) *

Sound Pressure Level (dBA) *

Min 85

Resonant Frequency (Hz) 2670

Remark: * rated voltage, 3KHz, 10cm, square wave, 1/2duty.

Mechanical, Environmental Parameter

Contact / Wire Pad

Operating Temperature (°C) -30 to +70

Storage Temperature (°C) -40 to +85

Material Housing n.a.

Color Housing Black

Component Weight (g, +/-o.2)

Remark:

<u>Approval</u>

RoHs ☑

UL \square

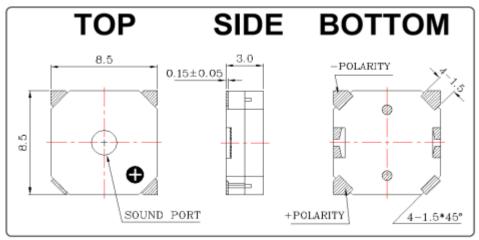
Designed by	MZ	16.05.2014	Dimensions without tolerance ±0.5mm Index: oc		Current date
Released by	СВ	16.05.2014	Drawing number	140516.1BS0	
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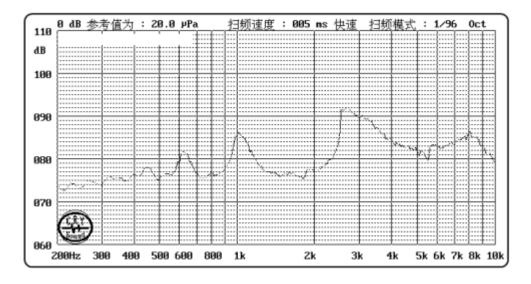
Drawing of Component

Unit:mm



Leading pin: Tin plated Brass(Sn)

Frequency Response

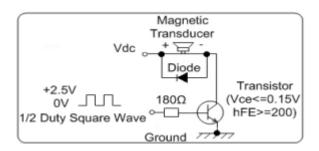


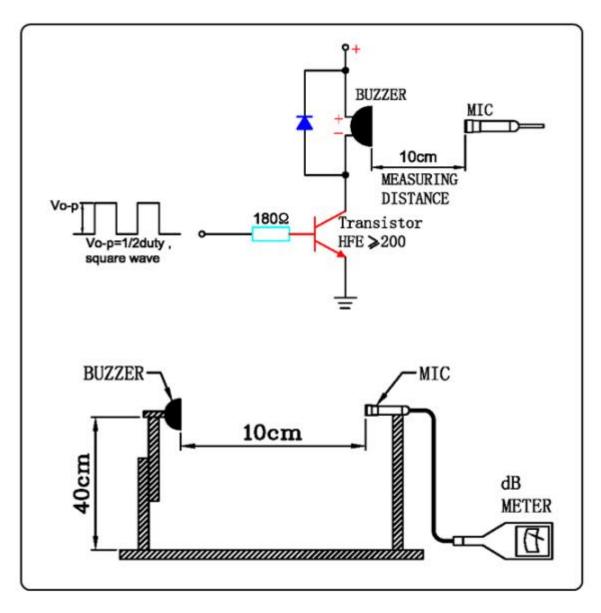
Designed by	MZ	16.05.2014	Dimensions without tolerance ±0.5mm Index: 00		Current date
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Test Method

Recommended Circuit





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Reliability Test

Requirement : Allowable variation of SPL after test: ±10dB.

a) HIGH TEMPERATURE TEST

After being placed in a chamber with 80±2°C for 96 hours and then being placed in normal condition for 2 hours.

b) LOW TEMPERATURE TEST

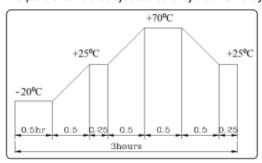
After being placed in a chamber with -30±2°C for 96 hours and then being placed in normal condition for 2 hours.

c) HUMIDITY TEST

After being placed in a chamber with 90-95% R.H. at 40±2°C for 96 hours and then being placed in normal condition for 2 hours.

d) TEMPERATURE CYCLE TEST

The part shall be subjected to 5 cycles. One cycle shall be consist of :



e) VIBRATION TEST

After being applied vibration of amplitude of 1.5mm with 10 to 55 Hz band of vibration frequency to each of 3 perpendicular directions for 2 hours.

f) DROP TEST

Drop on a hard wood board of 4cm thick, any directions ,6 times, at the height of 75cm.

g) SOLDERABILITY TEST

Lead terminals are immersed in rosin for 5 seconds and then immersed in solder bath of +300±5°C for 3±1 seconds. 90% min. lead terminals shall be wet with solder(Except the edge of terminals).

h) TERMINAL STRENGTH PULLING TEST

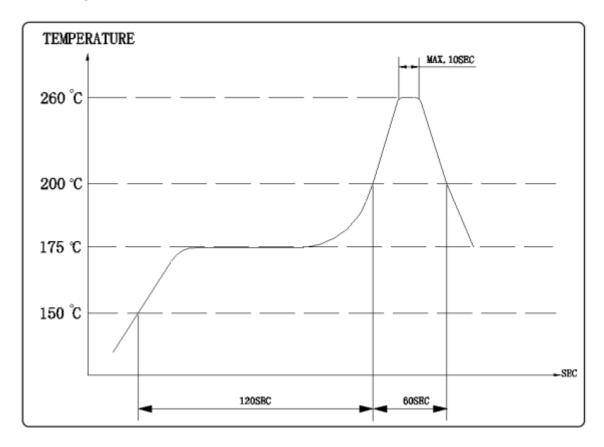
The force of 9.8N(1.0kg) is applied to each terminal in axial direction for 10 seconds. No visible damage and cutting off.

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DIGISOUND°

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Soldering Conditions

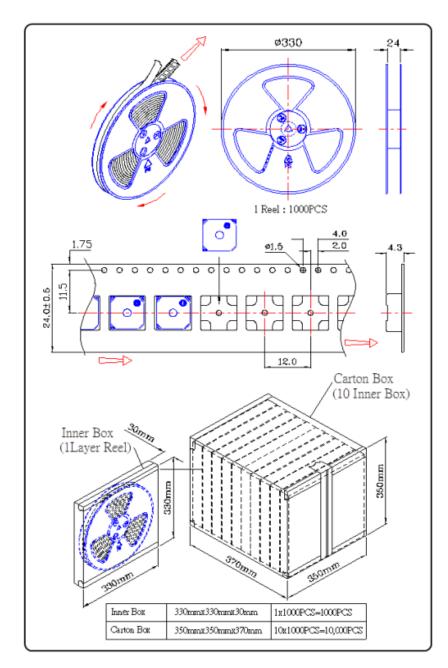


Solder profile according to JSTD020D-01

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Packaging Information



Revision Table

Index Nr.	Date Reason - Procedure Change description	Drawing Date	implementation LS-Nr.: Date	Comments

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